Zero-Drift, Rail-to-Rail I/O CMOS Operational Amplifiers

1 FEATURES

- **Low Offset Voltage: ±40μV (Max)**
- **Input Offset Drift: ±0.05μV/°C**
- **High Gain Bandwidth Product: 350KHz**
- **Rail-to-Rail Input and Output**
- **High Gain, CMRR, PSRR: 130dB**
- **High Slew Rate: 0.17V/μs**
- **Low Noise: 1.6μVp-p (0.01~10Hz)**
- **Low Power Consumption: 60μA /op amp**
- **Overload Recovery Time:6μs**
- **Low Supply Voltage: +2.3 V to +5.5 V**
- **No External Capacitors Required**
- **Extended Temperature: -40°C to +125°C**

2 APPLICATIONS

- **Temperature Sensors**
- **Medical/Industrial Instrumentation**
- **Pressure Sensors**
- **Battery-Powered Instrumentation**
- **Active Filtering**
- **Weight Scale Sensor**
- **Strain Gage Amplifiers**
- **Power Converter/Inverter**

3 DESCRIPTIONS

The RS8511, RS8512, RS8514 series of CMOS operational amplifiers use auto-zero techniques to simultaneously provide very low offset voltage (40μV max) and near-zero drift over time and temperature. This family of amplifiers has ultralow noise, offset and power.

This miniature, high-precision operational amplifiers offset high input impedance and rail-to-rail input and rail-to-rail output swing. With high gain-bandwidth product of 350KHz and slew rate of 0.17V/μs.

Single or dual supplies as low as +2.3V (±1.15V) and up to +5.5V (±2.75V) may be used.

The RS8511/ RS8512/ RS8514 are specified for the extended industrial and automotive temperature range (-40°C to 125°C). The RS8511 single amplifier is available in 5-lead SOT23 package, The RS8512 dual amplifier is available in 8-lead SOP, 8-lead DFN2X2 and 8-lead TSSOP narrow surface mount packages. The RS8514 quad is available in 14-lead SOP package.

Device Information (1)

PART NUMBER	PACKAGE	BODY SIZE(NOM)
RS8511	SOT23-5	2.90mm×1.60mm
RS8512	SOP8	4.90mm×3.90mm
	MSOP8	3.00mm×3.00mm
	DFN2X2-8	2.00mm×2.00mm
RS8514	SOP14	8.65mm×3.90mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.

Table of Contents

4 REVISION HISTORY

Note: Page numbers for previous revisions may different from page numbers in the current version.

Version	Change Date	Change Item
C.1	2022/06/02	1. Update Package Qty on Page 3 in RevB.7 2. Added TAPE AND REEL INFORMATION 3. Change Input Bias Current vs Temperature charts on Page 5 in RevB.7
C.2	2023/09/15	1. Added Pin Description 2. Delete RS8513 related content
C.2.1	2024/03/01	Modify packaging naming
C.3	2024/12/24	1. Delete RS8511XK/RS8511XM/RS8514XQ Orderable Device 2. Add MSL on Page 4 in RevC.2.1

5 PACKAGE/ORDERING INFORMATION (1)

Orderable Device	Package Type	Pin	Channel	Op Temp(°C)	Device Marking (2)	MSL (3)	Package Qty
RS8511XF	SOT23-5	5	1	-40°C ~125°C	8511	MSL3	Tape and Reel,3000
RS8511BXF	SOT23-5	5	1	-40°C ~125°C	8511B	MSL3	Tape and Reel,3000
RS8512XK	SOP8	8	2	-40°C ~125°C	RS8512	MSL3	Tape and Reel,4000
RS8512XM	MSOP8	8	2	-40°C ~125°C	RS8512	MSL3	Tape and Reel,4000
RS8512XTDE8	DFN2X2-8	8	2	-40°C ~125°C	8512	MSL3	Tape and Reel,3000
RS8514XP	SOP14	14	4	-40°C ~125°C	RS8514	MSL3	Tape and Reel,4000

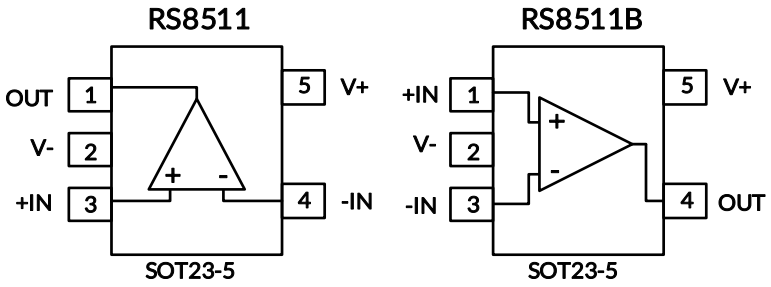
NOTE:

(1) This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the right-hand navigation.

(2) There may be additional marking, which relates to the lot trace code information (data code and vendor code), the logo or the environmental category on the device.

(3) RUNIC classify the MSL level with using the common preconditioning setting in our assembly factory conforming to the JEDEC industrial standard J-STD-20F. Please align with RUNIC if your end application is quite critical to the preconditioning setting or if you have special requirement.

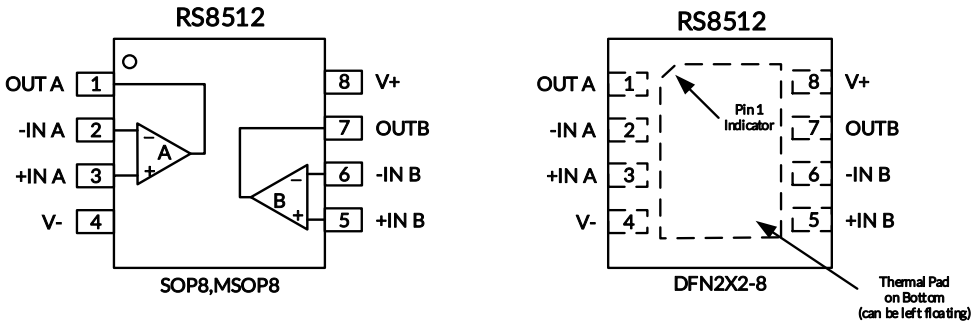
6 PIN CONFIGURATION AND FUNCTIONS



Pin Description

NAME	PIN		I/O (1)	DESCRIPTION
	RS8511	RS8511B		
	SOT23-5	SOT23-5		
-IN	4	3	I	Negative (inverting) input
+IN	3	1	I	Positive (noninverting) input
OUT	1	4	O	Output
V-	2	2	-	Negative (lowest) power supply
V+	5	5	-	Positive (highest) power supply

(1) I = Input, O = Output.

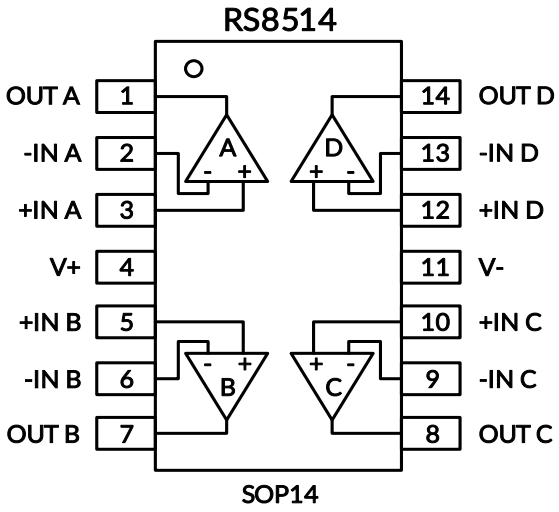


Pin Description

NAME	PIN	I/O (1)	DESCRIPTION
	SOP8/MSOP8/DFN2X2-8		
-INA	2	I	Inverting input, channel A
+INA	3	I	Noninverting input, channel A
-INB	6	I	Inverting input, channel B
+INB	5	I	Noninverting input, channel B
OUTA	1	O	Output, channel A
OUTB	7	O	Output, channel B
V-	4	-	Negative (lowest) power supply
V+	8	-	Positive (highest) power supply
-	Thermal Pad	-	Connect thermal pad to V-

(1) I = Input, O = Output.

PIN CONFIGURATION AND FUNCTIONS



Pin Description

NAME	PIN	I/O (1)	DESCRIPTION
	SOP14		
-INA	2	I	Inverting input, channel A
+INA	3	I	Noninverting input, channel A
-INB	6	I	Inverting input, channel B
+INB	5	I	Noninverting input, channel B
-INC	9	I	Inverting input, channel C
+INC	10	I	Noninverting input, channel C
-IND	13	I	Inverting input, channel D
+IND	12	I	Noninverting input, channel D
OUTA	1	O	Output, channel A
OUTB	7	O	Output, channel B
OUTC	8	O	Output, channel C
OUTD	14	O	Output, channel D
V-	11	-	Negative (lowest) power supply
V+	4	-	Positive (highest) power supply

(1) I = Input, O = Output.

7 SPECIFICATIONS

7.1 Absolute Maximum Ratings

Over operating free-air temperature range (unless otherwise noted) (1)

			MIN	MAX	UNIT
Voltage	Supply, V_S=(V+) - (V-)			7	V
	Signal input pin (2)		(V-)-0.5	(V+) +0.5	
	Signal output pin (3)		(V-)-0.5	(V+) +0.5	
Current	Signal input pin (2)		-10	10	mA
	Signal output pin (3)		-55	55	mA
	Output short-circuit (4)		Continuous		
θ_{JA}	Package thermal impedance (5)	SOT23-5		230	°C/W
		SOP8		110	
		MSOP8		170	
		SOP14		105	
		DFN2X2-8		80	
Temperature	Operating range, T_A		-40	125	°C
	Junction, T_J (6)		-40	150	
	Storage, T_{stg}		-65	150	

(1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those specified is not implied.
(2) Input terminals are diode-clamped to the power-supply rails. Input signals that can swing more than 0.5V beyond the supply rails should be current-limited to 10mA or less.
(3) Output terminals are diode-clamped to the power-supply rails. Output signals that can swing more than 0.5V beyond the supply rails should be current-limited to ±55mA or less.
(4) Short-circuit to ground, one amplifier per package.
(5) The package thermal impedance is calculated in accordance with JESD-51.
(6) The maximum power dissipation is a function of $T_{J(MAX)}$, $R_{\theta JA}$, and T_A. The maximum allowable power dissipation at any ambient temperature is $P_D = (T_{J(MAX)} - T_A) / R_{\theta JA}$. All numbers apply for packages soldered directly onto a PCB.

7.2 ESD Ratings

The following ESD information is provided for handling of ESD-sensitive devices in an ESD protected area only.

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human-Body Model (HBM)	±5000	V
		Machine Model (MM)	±400	

ESD SENSITIVITY CAUTION

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

7.3 Recommended Operating Conditions

Over operating free-air temperature range (unless otherwise noted)

		MIN	NOM	MAX	UNIT
Supply voltage, Vs= (V+) - (V-)	Single-supply	2.3		5.5	V
	Dual-supply	±1.15		±2.75	

7.4 Electrical Characteristics

Boldface limits apply over the specified temperature range, T_A [9] = -40°C to +125°C.
(At T_A = +25°C, V_S=5V, R_L = 10kΩ connected to V_S/2, and V_{OUT} = V_S/2, V_{CM} = V_S/2, unless otherwise noted.) [1]

PARAMETER	SYMBOL	CONDITION	T_J	RS8511, RS8512, RS8514			
				MIN[2]	TYP[3]	MAX[2]	UNIT
OFFSET VOLTAGE							
Input Offset Voltage	V_{OS}	V_{CM}= V_S/2	25°C	-40	±7	40	μV
Input Offset Voltage Average Drift	Vos Tc	V_{CM}= V_S/2	25°C		±0.05	±0.2	μV/°C
Power-Supply Rejection Ratio	PSRR	V_S= +2.3V to +5.5V, V_{CM}= 0	25°C	110	130		dB
Channel Separation, dc			25°C		0.1		μV/V
INPUT BIAS CURRENT							
Input Bias Current [4] [5]	IB	V_{CM} = V_S/2	25°C		±50		pA
Input Offset Current [4]	I_{OS}		25°C		±10		pA
NOISE PERFORMANCE							
Input Voltage Noise	e_np-p	f= 0.01Hz to 10Hz	25°C		1.6		μVpp
Input Voltage Noise	e_np-p	f= 0.01Hz to 1Hz	25°C		0.48		μVpp
Input Voltage Noise Density	e_n	f= 1KHz	25°C		70		nV/$\sqrt{Hz}$
Input Current Noise Density	i_n	f= 10Hz	25°C		8		fA/$\sqrt{Hz}$
INPUT VOLTAGE RANGE							
Common-Mode Voltage Range	V_{CM}		25°C	(V-)-0.1		(V+)+0.1	V
Common-Mode Rejection Ratio	CMRR	(V-)-0.1V < V_{CM} < (V+)+0.1V	25°C	110	130		dB
INPUT CAPACITANCE							
Differential			25°C		1		pF
Common-Mode			25°C		5		pF
Open-Loop Gain							
Open-Loop Voltage Gain	A_{OL}	R_L=10KΩ, V_O=0.3V to 4.7V	Full	110	130		dB
DYNAMIC PERFORMANCE							
Slew Rate [8]	SR	G= +1	25°C		0.17		V/μs
Gain-Bandwidth Product	GBW		25°C		350		KHz
Overload Recovery Time	t_{OR}		25°C		6		μs
OUTPUT CHARACTERISTICS							
Output Voltage High	V_{OH}	R_L=100 KΩ to GND	25°C	4.99	4.998		V
		R_L=10 KΩ to GND	25°C	4.95	4.98		
Output Voltage Low	V_{OL}	R_L=100 KΩ to V+	25°C		1	10	mV
		R_L=10 KΩ to V+	25°C		10	30	
Short-Circuit Current [6] [7]	I_{SC}		25°C		±25		mA
POWER SUPPLY							
Operating Voltage Range	V_S		25°C	2.3		5.5	V
Quiescent Current Per Amplifier	I_Q		25°C		60	87	μA

NOTE:

(1) Electrical table values apply only for factory testing conditions at the temperature indicated. Factory testing conditions result in very limited self-heating of the device.

(2) Limits are 100% production tested at 25°C. Limits over the operating temperature range are ensured through correlations using statistical quality control (SQC) method.

(3) Typical values represent the most likely parametric norm as determined at the time of characterization. Actual typical values may vary over time and will also depend on the application and configuration.

(4) This parameter is ensured by design and/or characterization and is not tested in production.

(5) Positive current corresponds to current flowing into the device.

(6) The maximum power dissipation is a function of $T_{J(MAX)}$, $R_{\theta JA}$, and T_A. The maximum allowable power dissipation at any ambient temperature is PD = ($T_{J(MAX)}$ - T_A) / $R_{\theta JA}$. All numbers apply for packages soldered directly onto a PCB.

(7) Short circuit test is a momentary test.

(8) Number specified is the slower of positive and negative slew rates.

(9) Specified by characterization only.

7.5 Typical Characteristics

NOTE: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only.

At T_A = +25°C, V_S=5V, R_L = 10kΩ connected to $V_S/2$, V_{OUT} = $V_S/2$, unless otherwise noted.

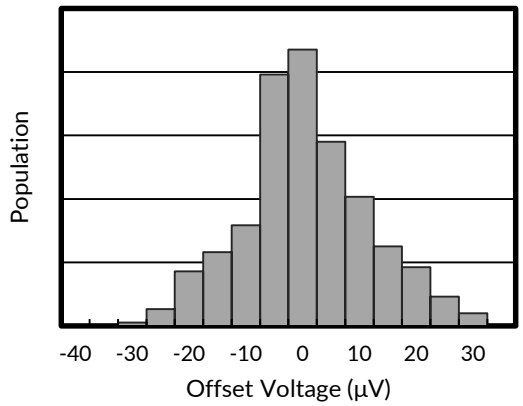


Figure 1. Offset Voltage Production Distribution

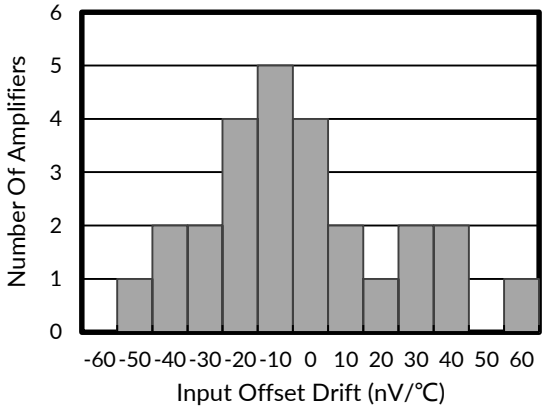


Figure 2. Offset Voltage Drift Production Distribution

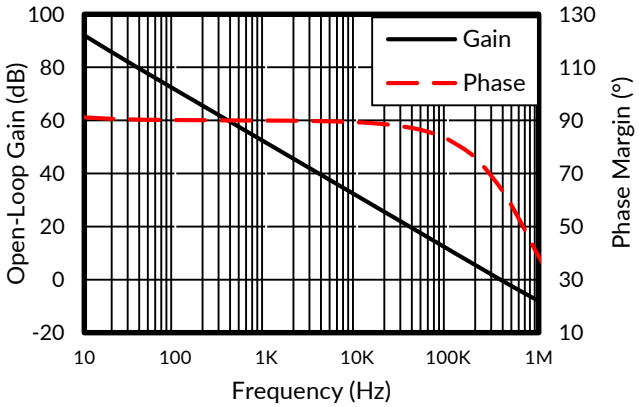


Figure 3. Open-Loop Gain and Phase vs Frequency

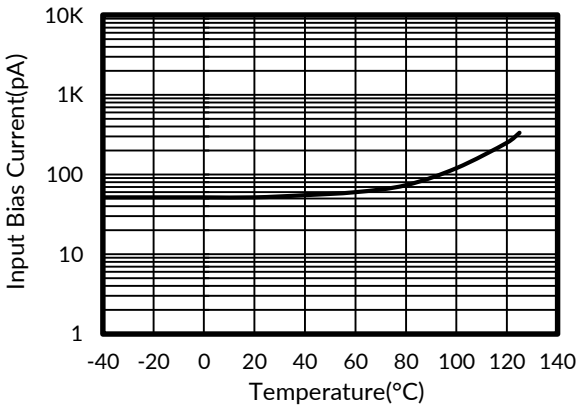


Figure 4. Input Bias Current vs Temperature

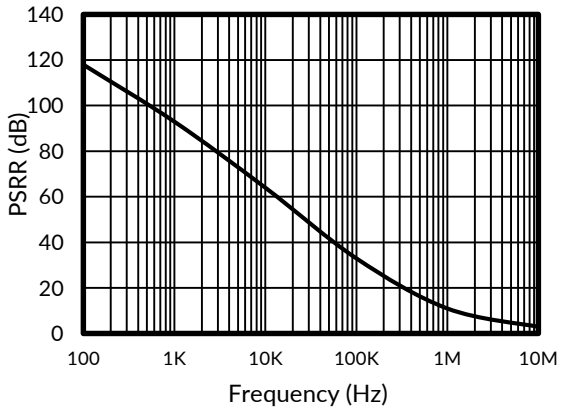


Figure 5. Power-Supply Rejection Ratio vs Frequency

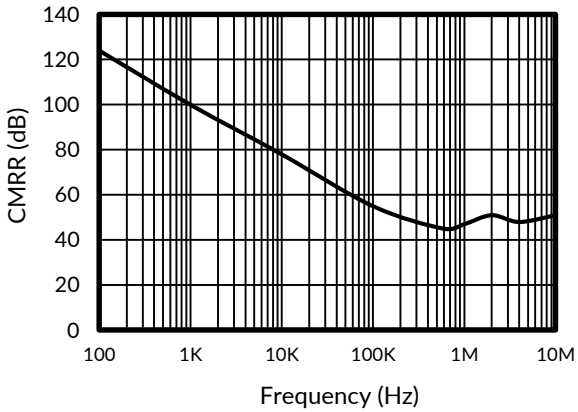


Figure 6. Common-Mode Rejection Ratio vs Frequency

Typical Characteristics

NOTE: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only.

At T_A = +25°C, V_S=5V, R_L = 10kΩ connected to $V_S/2$, V_{OUT} = $V_S/2$, unless otherwise noted.

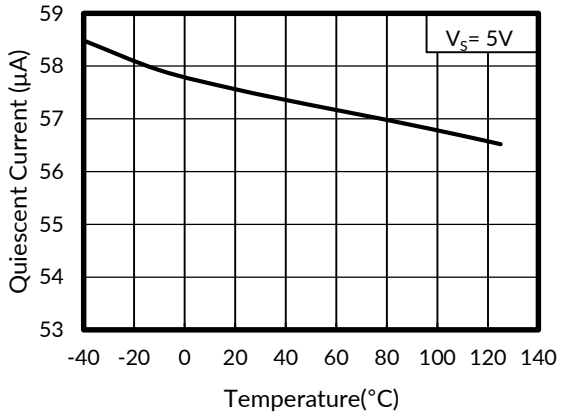


Figure 7. Quiescent Current vs Temperature

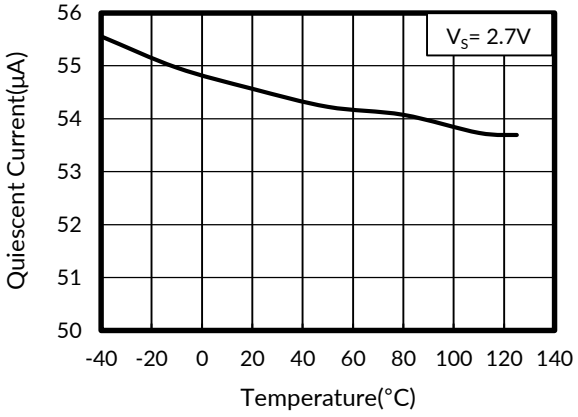


Figure 8. Quiescent Current vs Temperature

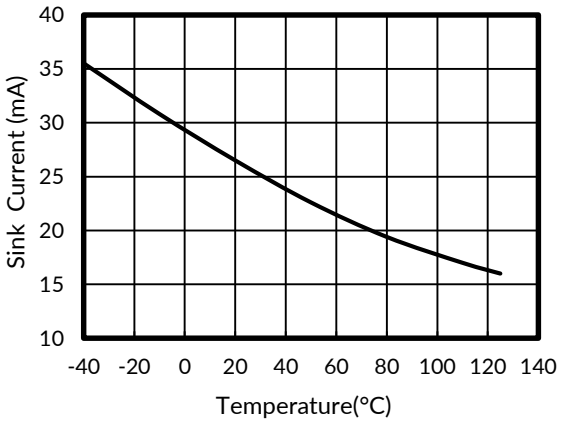


Figure 9. Sink Current vs Temperature

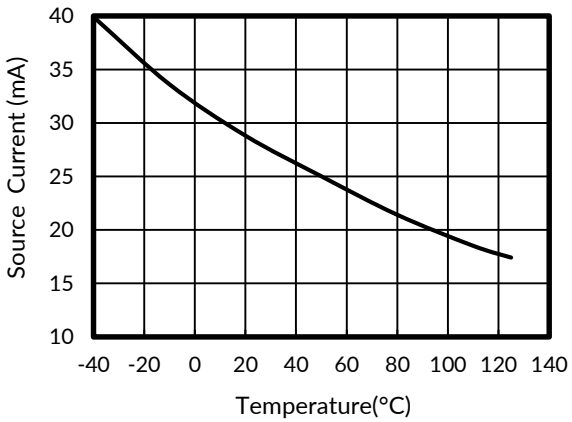


Figure 10. Source Current vs Temperature

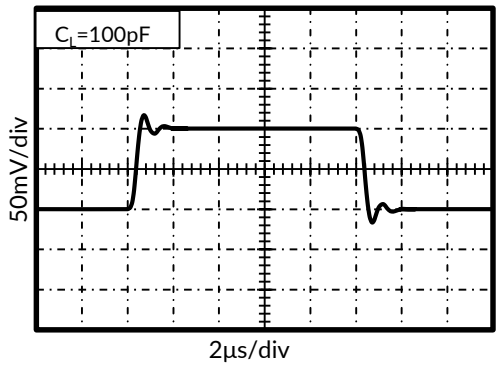


Figure 11. Small-Signal Step Response

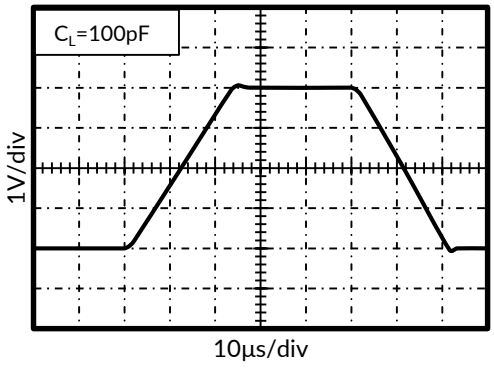


Figure 12. Large-Signal Step Response

Typical Characteristics

NOTE: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only.

At T_A = +25°C, V_S=5V, R_L = 10kΩ connected to $V_S/2$, V_{OUT} = $V_S/2$, unless otherwise noted.

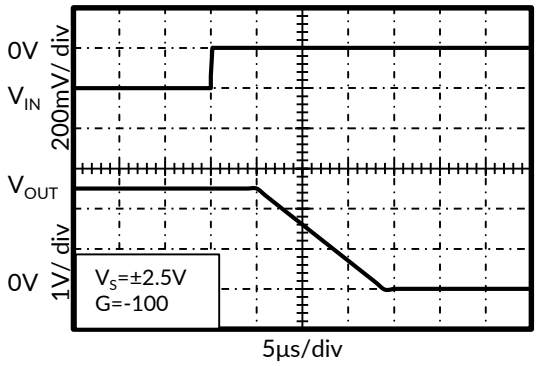


Figure 13. Positive Overvoltage Recovery

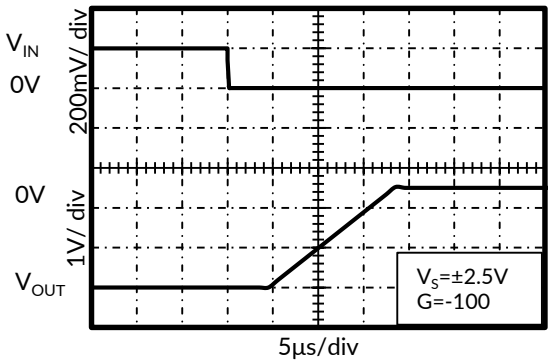


Figure 14. Negative Overvoltage Recovery

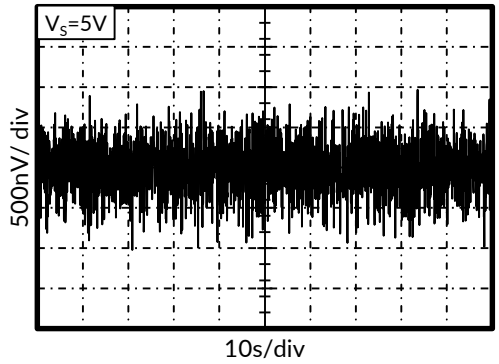


Figure 15. 0.01Hz to 10Hz Noise

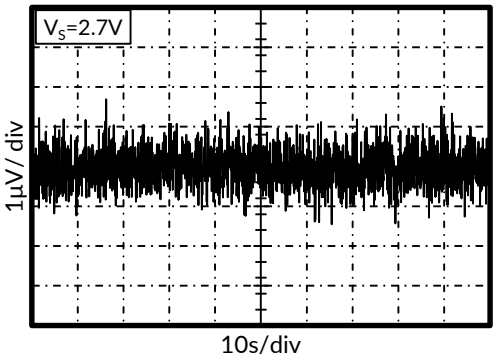


Figure 16. 0.01Hz to 10Hz Noise

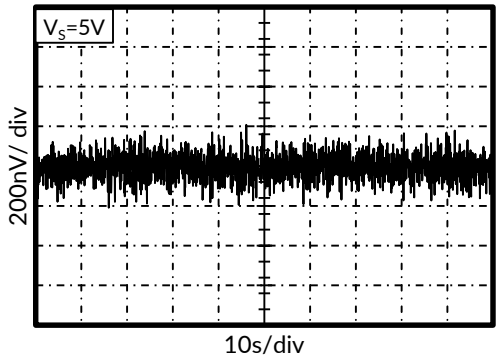


Figure 17. 0.01Hz to 1Hz Noise

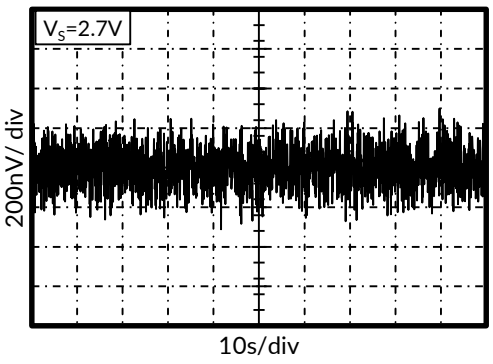


Figure 18. 0.01Hz to 1Hz Noise

8 DETAILED DESCRIPTION

8.1 Overview

The RS8511, RS8512, RS8514 series op amps are unity-gain stable and free from unexpected output phase reversal. They use auto-zeroing techniques to provide low offset voltage and very low drift over time and temperature.

Good layout practice mandates use of a 0.1μF capacitor placed closely across the supply pins. For lowest offset voltage and precision performance, circuit layout and mechanical conditions should be optimized. Avoid temperature gradients that create thermoelectric (Seebeck) effects in thermocouple junctions formed from connecting dissimilar conductors. These thermally-generated potentials can be made to cancel by assuring that they are equal on both input terminals.

- Use low thermoelectric-coefficient connections (avoid dissimilar metals).
- Thermally isolate components from power supplies or other heat-sources.
- Shield op amp and input circuitry from air currents, such as cooling fans.

Following these guidelines will reduce the likelihood of junctions being at different temperatures, which can cause thermoelectric voltages of 0.1μV/°C or higher, depending on materials used.

8.2 Operating Voltage

The RS8511, RS8512, RS8514 series op amps operate over a power-supply range of +2.3V to +5.5V (±1.15V to ±2.75V). Supply voltages higher than 7V (absolute maximum) can permanently damage the amplifier. Parameters that vary over supply voltage or temperature are shown in the Typical Characteristics section of this data sheet.

9 LAYOUT

9.1 Layout Guidelines

Attention to good layout practices is always recommended. Keep traces short. When possible, use a PCB ground plane with surface-mount components placed as close to the device pins as possible. Place a 0.1μF capacitor closely across the supply pins.

These guidelines should be applied throughout the analog circuit to improve and provide benefits such as reducing the EMI susceptibility.

9.2 Layout Example

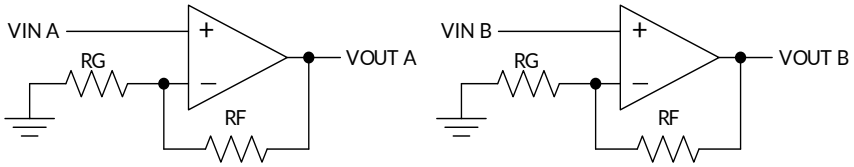


Figure 19. Schematic Representation

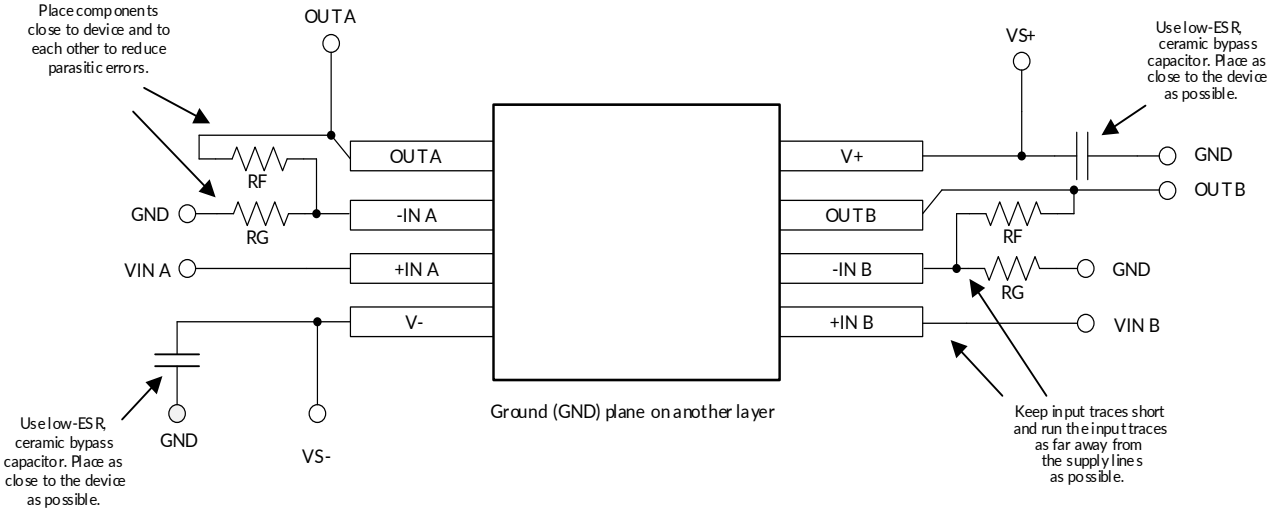
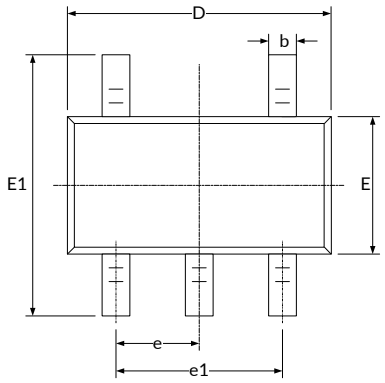


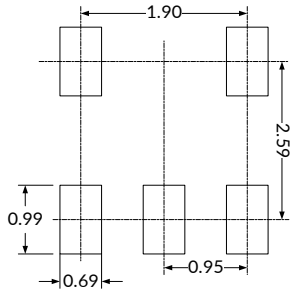
Figure 20. Layout Example

NOTE: Layout Recommendations have been shown for dual op-amp only, follow similar precautions for Single and four.

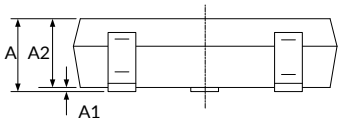
10 PACKAGE OUTLINE DIMENSIONS

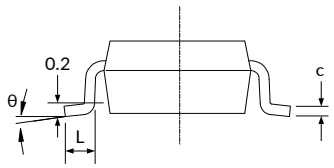
SOT23-5 (3)





RECOMMENDED LAND PATTERN (Unit: mm)



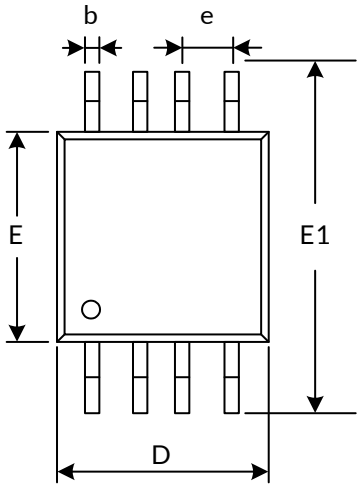


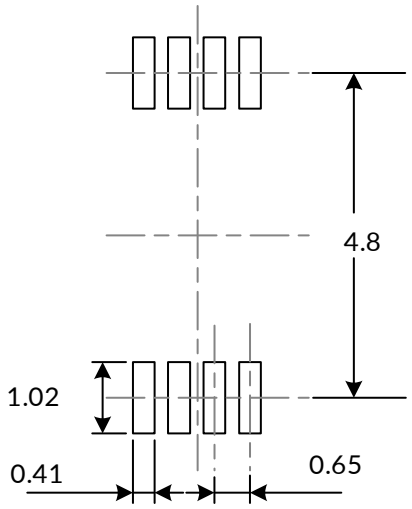
Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A (1)	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D (1)	2.820	3.020	0.111	0.119
E (1)	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950(BSC) (2)		0.037(BSC) (2)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°

NOTE:

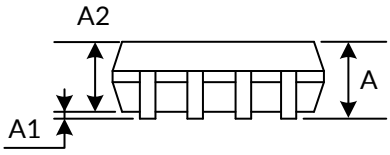
1. Plastic or metal protrusions of 0.15mm maximum per side are not included.
2. BSC (Basic Spacing between Centers), "Basic" spacing is nominal.
3. This drawing is subject to change without notice.

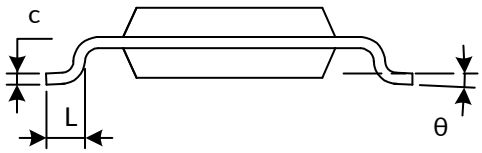
MSOP8 (3)





RECOMMENDED LAND PATTERN (Unit: mm)



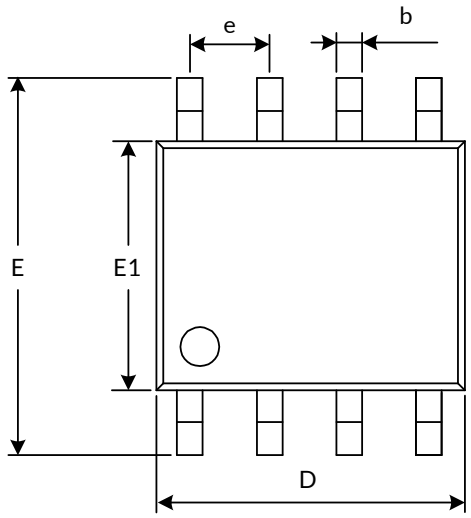


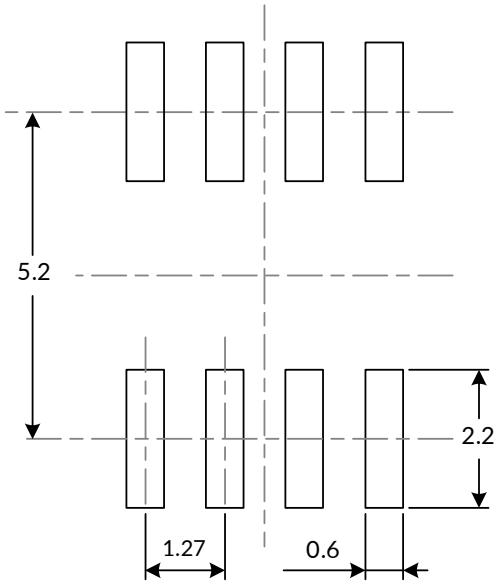
Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A (1)	0.820	1.100	0.032	0.043
A1	0.020	0.150	0.001	0.006
A2	0.750	0.950	0.030	0.037
b	0.250	0.380	0.010	0.015
c	0.090	0.230	0.004	0.009
D (1)	2.900	3.100	0.114	0.122
e	0.650(BSC) (2)		0.026(BSC) (2)	
E (1)	2.900	3.100	0.114	0.122
E1	4.750	5.050	0.187	0.199
L	0.400	0.800	0.016	0.031
θ	0°	6°	0°	6°

NOTE:

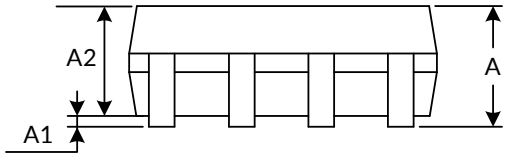
1. Plastic or metal protrusions of 0.15mm maximum per side are not included.
2. BSC (Basic Spacing between Centers), "Basic" spacing is nominal.
3. This drawing is subject to change without notice.

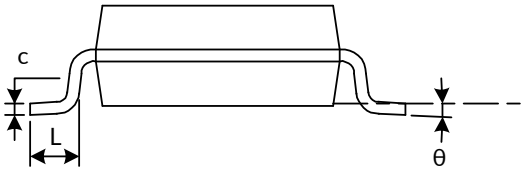
SOP8 (3)





RECOMMENDED LAND PATTERN (Unit: mm)



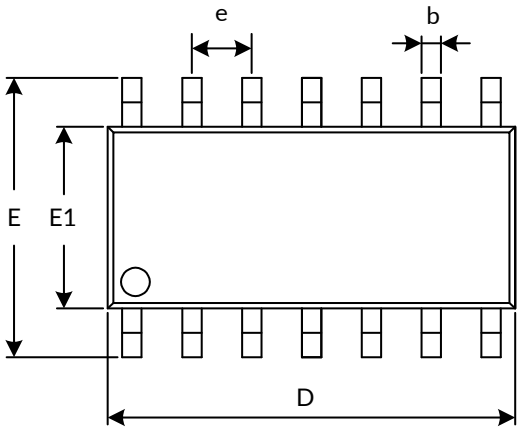


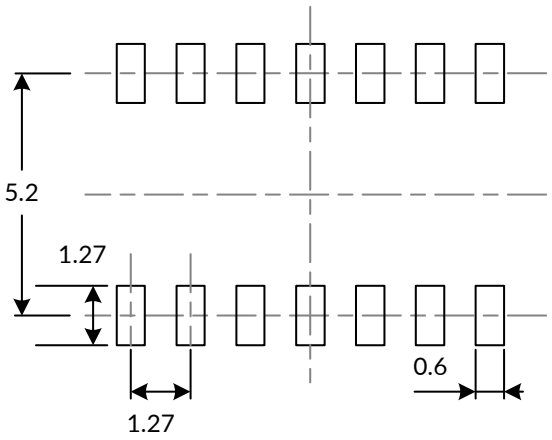
Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A (1)	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.007	0.010
D (1)	4.800	5.000	0.189	0.197
e	1.270(BSC) (2)		0.050(BSC) (2)	
E	5.800	6.200	0.228	0.244
E1 (1)	3.800	4.000	0.150	0.157
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

NOTE:

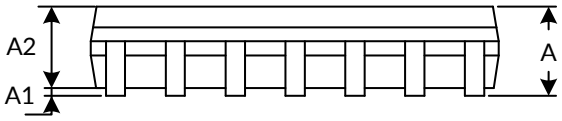
1. Plastic or metal protrusions of 0.15mm maximum per side are not included.
2. BSC (Basic Spacing between Centers), "Basic" spacing is nominal.
3. This drawing is subject to change without notice.

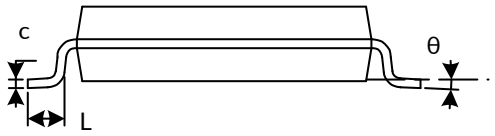
SOP14 (3)





RECOMMENDED LAND PATTERN (Unit: mm)



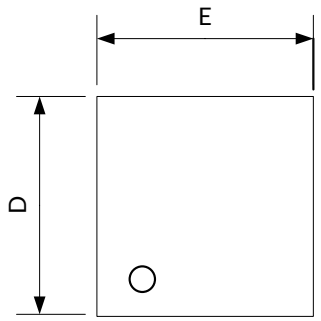


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A (1)	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.310	0.510	0.012	0.020
c	0.100	0.250	0.004	0.010
D (1)	8.450	8.850	0.333	0.348
e	1.270(BSC) (2)		0.050(BSC) (2)	
E	5.800	6.200	0.228	0.244
E1 (1)	3.800	4.000	0.150	0.157
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

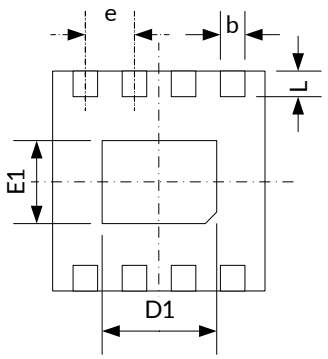
NOTE:

1. Plastic or metal protrusions of 0.15mm maximum per side are not included.
2. BSC (Basic Spacing between Centers), "Basic" spacing is nominal.
3. This drawing is subject to change without notice.

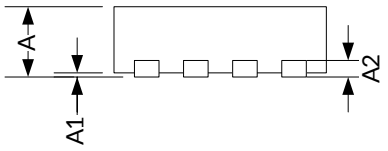
DFN2X2-8 (2)



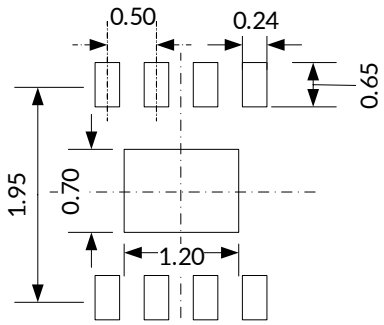
TOP VIEW



BOTTOM VIEW



SIDE VIEW



RECOMMENDED LAND PATTERN
(Unit: mm)

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A (1)	0.700	0.800	0.028	0.031
A1	0.000	0.050	0.000	0.002
A2	0.203(TYP)		0.008(TYP)	
b	0.180	0.300	0.007	0.012
D (1)	1.900	2.100	0.075	0.083
D1	1.100	1.300	0.043	0.051
E (1)	1.900	2.100	0.075	0.083
E1	0.600	0.800	0.024	0.031
e	0.500(TYP)		0.020(TYP)	
L	0.250	0.450	0.010	0.018

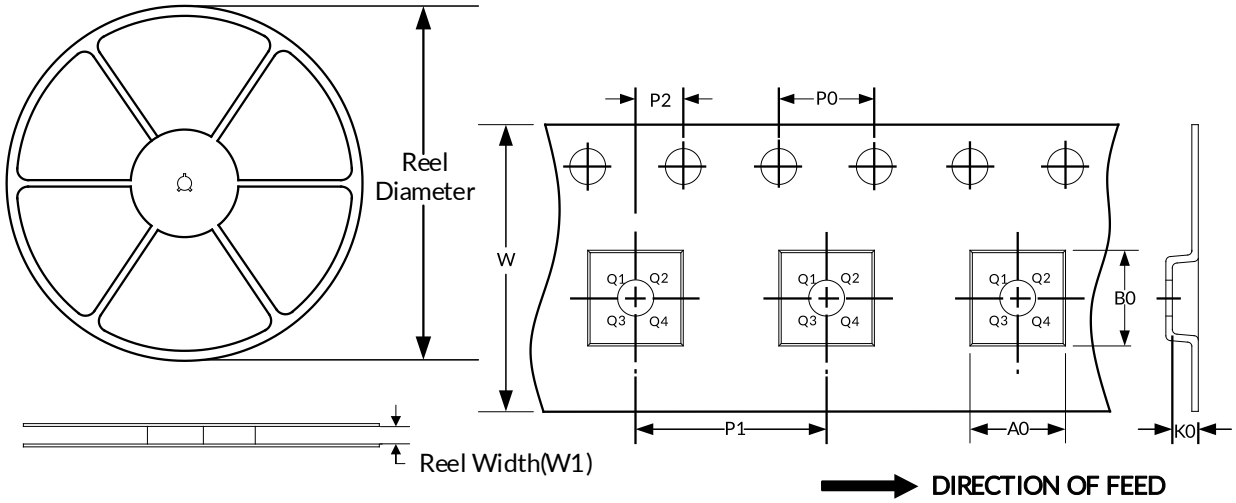
NOTE:

1. Plastic or metal protrusions of 0.075mm maximum per side are not included.
2. This drawing is subject to change without notice.

11 TAPE AND REEL INFORMATION

REEL DIMENSIONS

TAPE DIMENSION



NOTE: The picture is only for reference. Please make the object as the standard.

KEY PARAMETER LIST OF TAPE AND REEL

Package Type	Reel Diameter	Reel Width (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P0 (mm)	P1 (mm)	P2 (mm)	W (mm)	Pin1 Quadrant
SOT23-5	7”	9.5	3.20	3.20	1.40	4.0	4.0	2.0	8.0	Q3
MSOP8	13”	12.4	5.20	3.30	1.50	4.0	8.0	2.0	12.0	Q1
SOP8	13”	12.4	6.40	5.40	2.10	4.0	8.0	2.0	12.0	Q1
SOP14	13”	16.4	6.60	9.30	2.10	4.0	8.0	2.0	16.0	Q1
DFN2X2-8	7”	9.5	2.30	2.30	1.10	4.0	4.0	2.0	8.0	Q2

NOTE:
1. All dimensions are nominal.
2. Plastic or metal protrusions of 0.15mm maximum per side are not included.

IMPORTANT NOTICE AND DISCLAIMER

Jiangsu RUNIC Technology Co., Ltd. will accurately and reliably provide technical and reliability data (including data sheets), design resources (including reference designs), application or other design advice, WEB tools, safety information and other resources, without warranty of any defect, and will not make any express or implied warranty, including but not limited to the warranty of merchantability Implied warranty that it is suitable for a specific purpose or does not infringe the intellectual property rights of any third party.

These resources are intended for skilled developers designing with RUNIC products You will be solely responsible for: (1) Selecting the appropriate products for your application; (2) Designing, validating and testing your application; (3) Ensuring your application meets applicable standards and any other safety, security or other requirements; (4) RUNIC and the RUNIC logo are registered trademarks of RUNIC INCORPORATED. All trademarks are the property of their respective owners; (5) For change details, review the revision history included in any revised document. The resources are subject to change without notice. Our company will not be liable for the use of this product and the infringement of patents or third-party intellectual property rights due to its use.